

This cross-sectional view shows a trench structure in a substrate (1). A conductive layer (6) is deposited within the trench, and a dielectric layer (2) is formed on the top surface of the substrate. The trench is filled with a material (1a) that has a different hatching pattern than the substrate.

FIG. 2

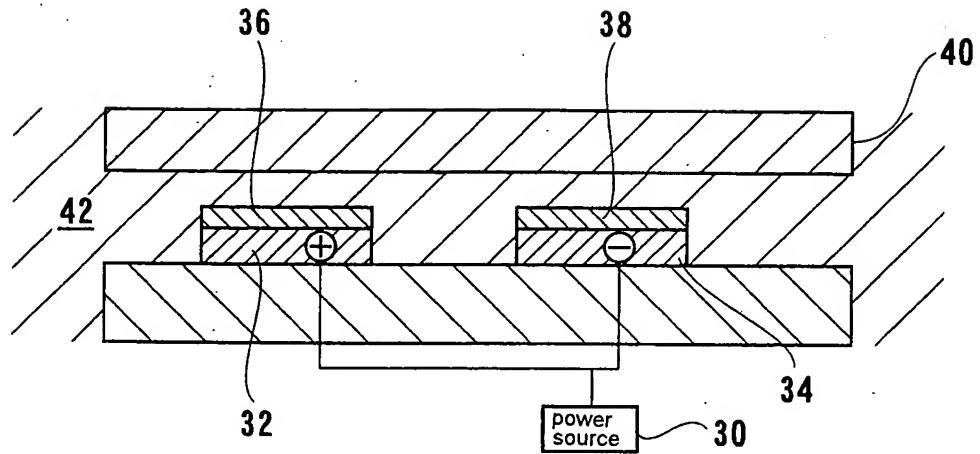


FIG. 3

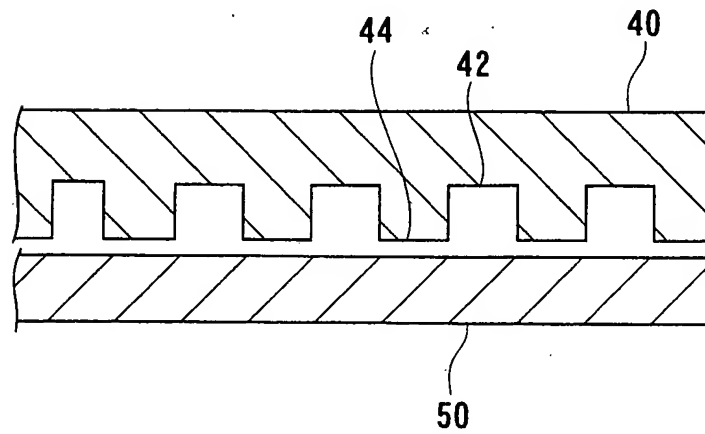


FIG. 4

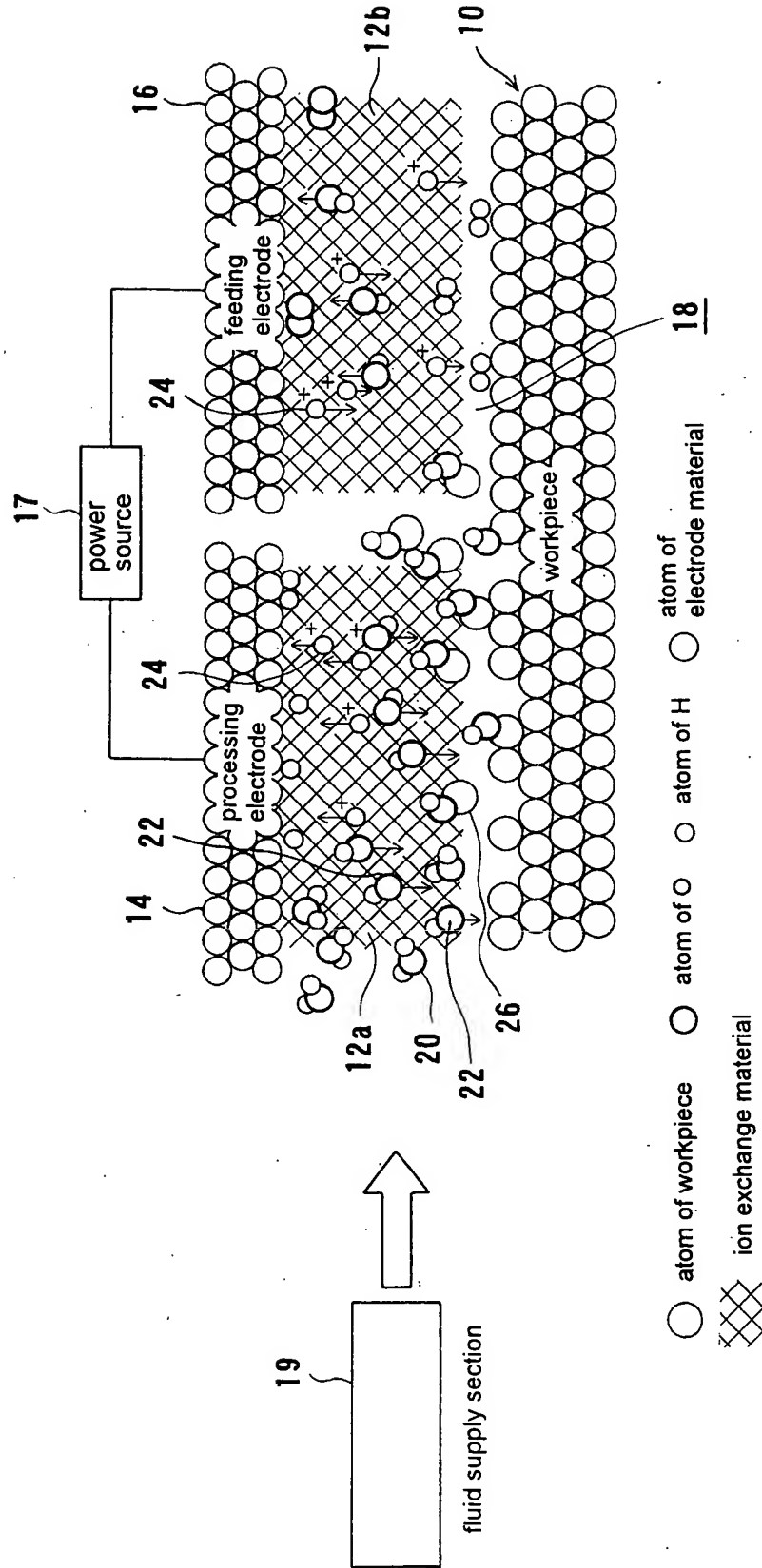


FIG. 5

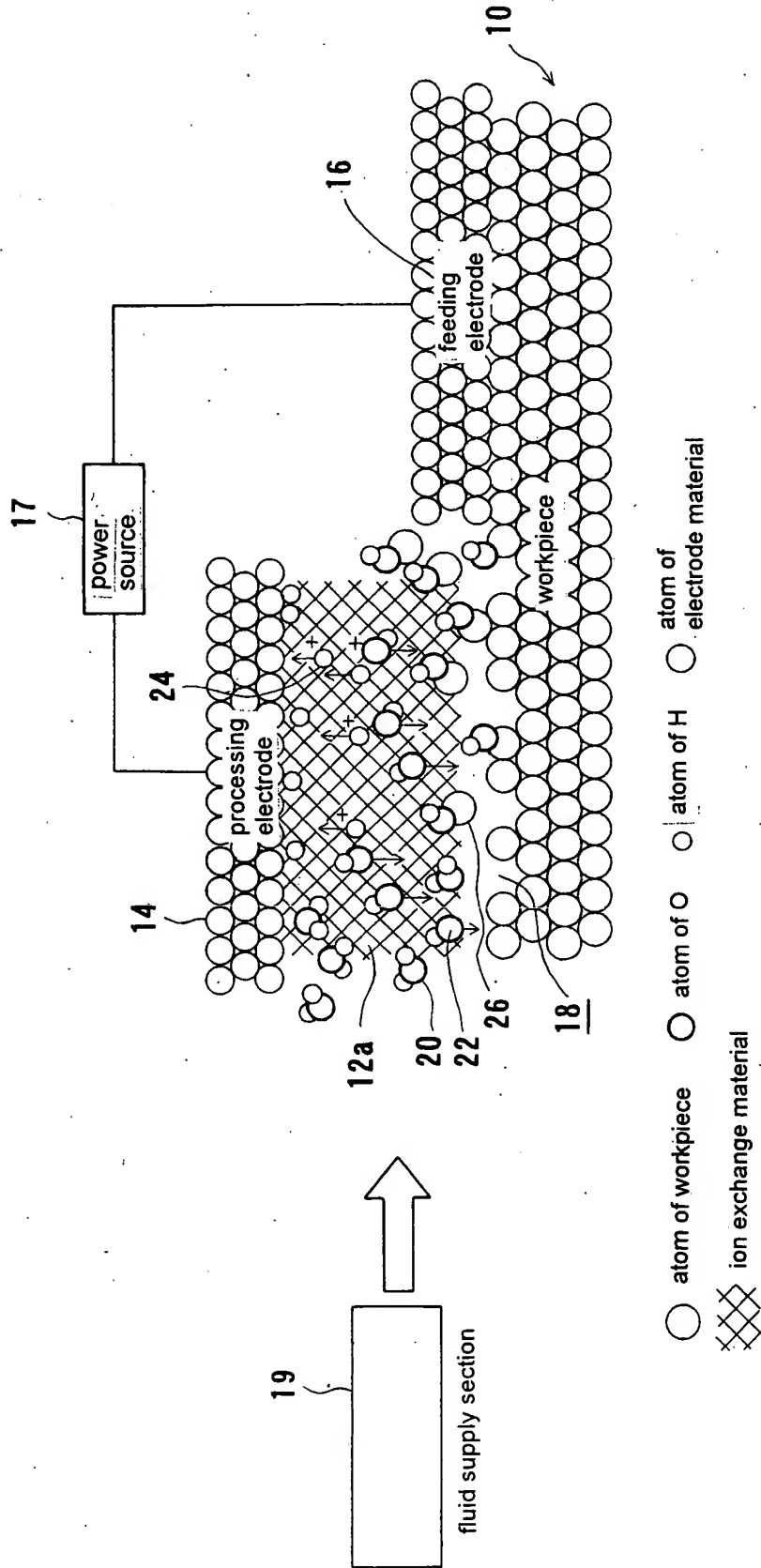
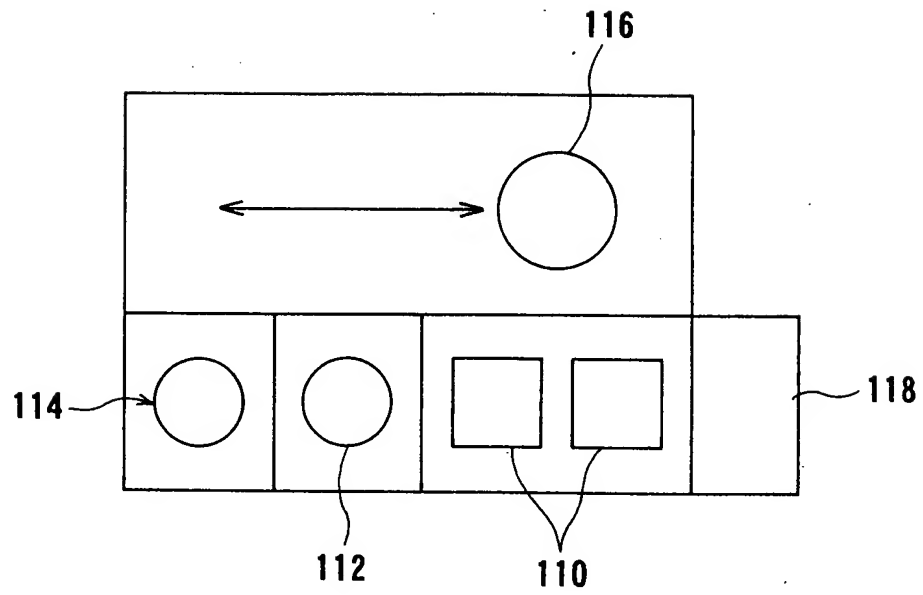


FIG. 6



**FIG. 7**

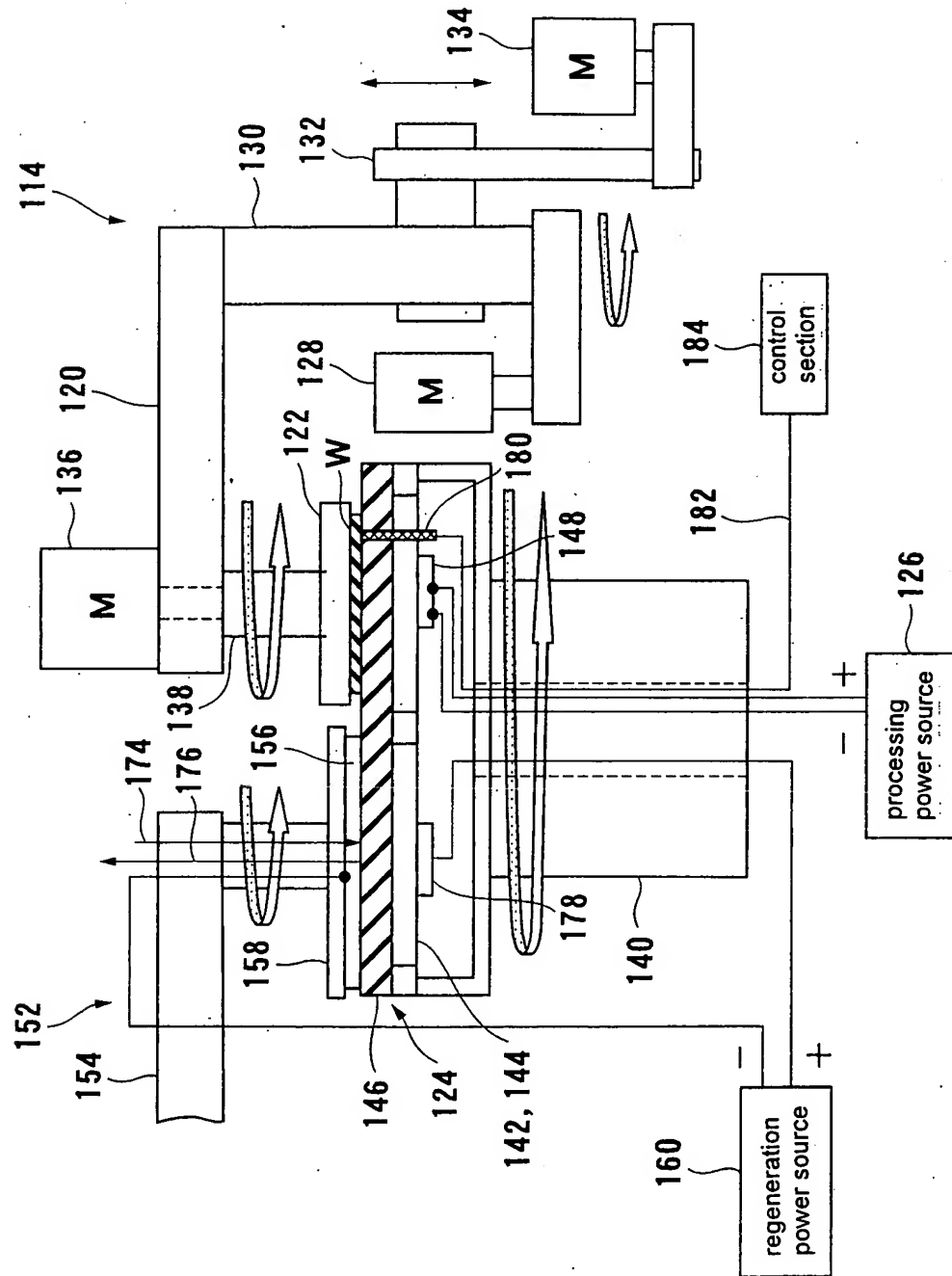


FIG. 8

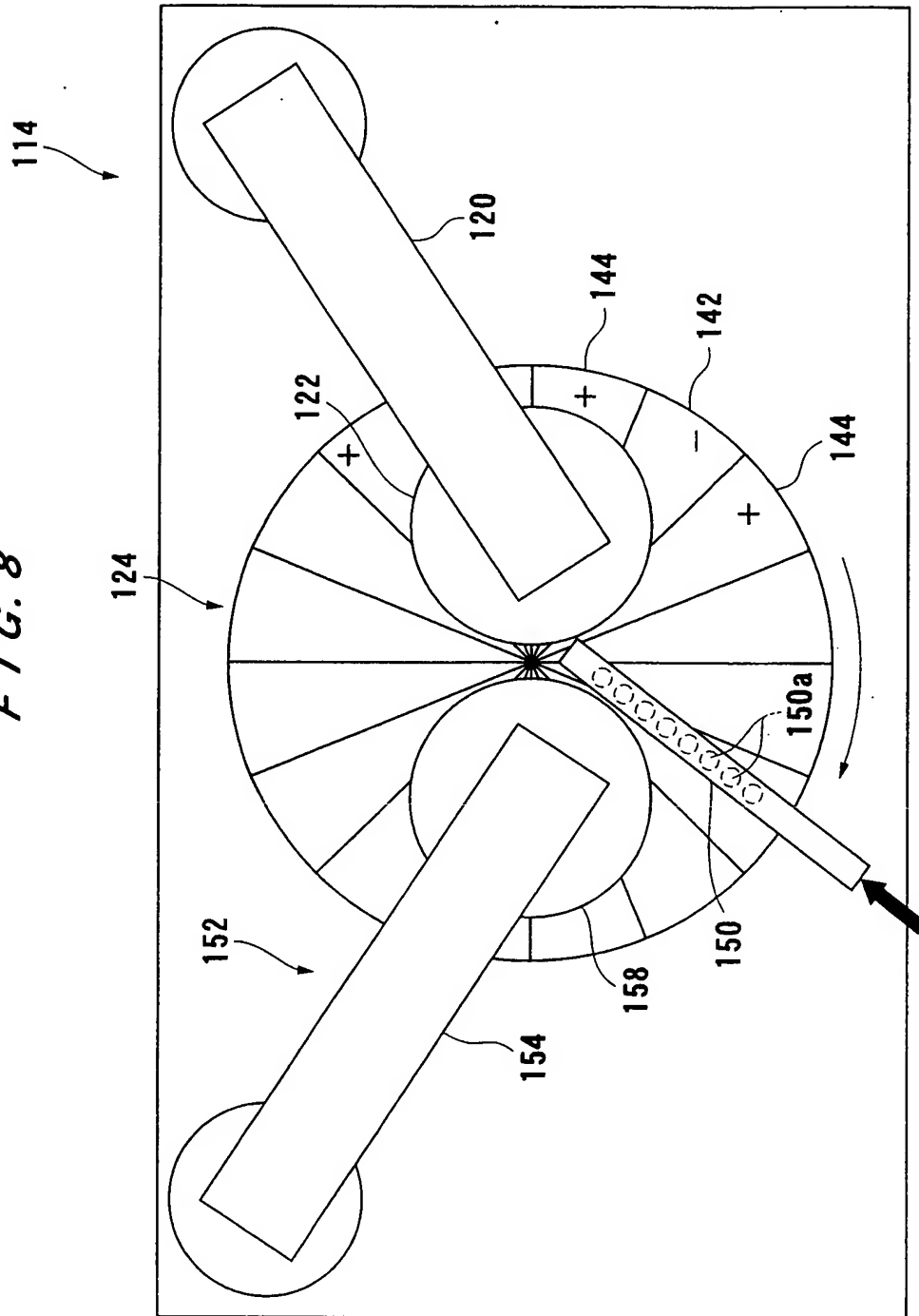
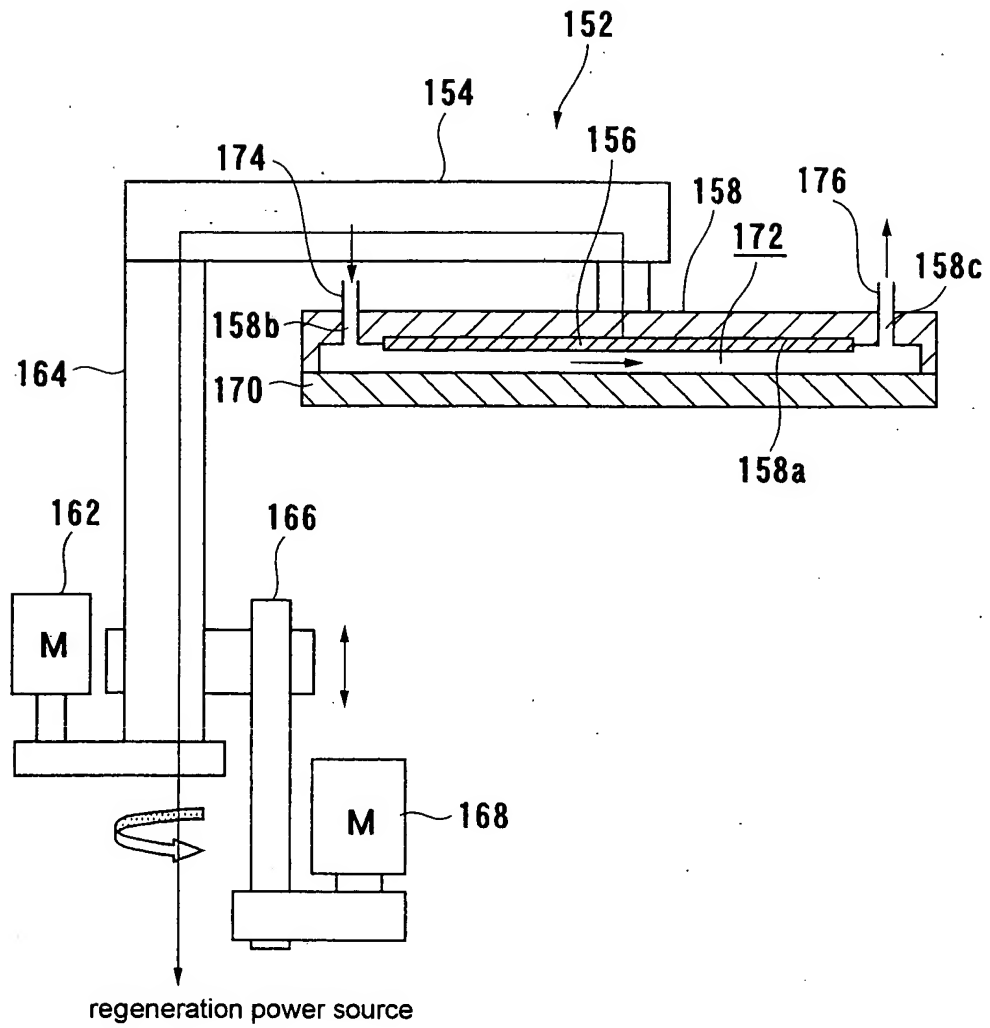


FIG. 9





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FIG. 10

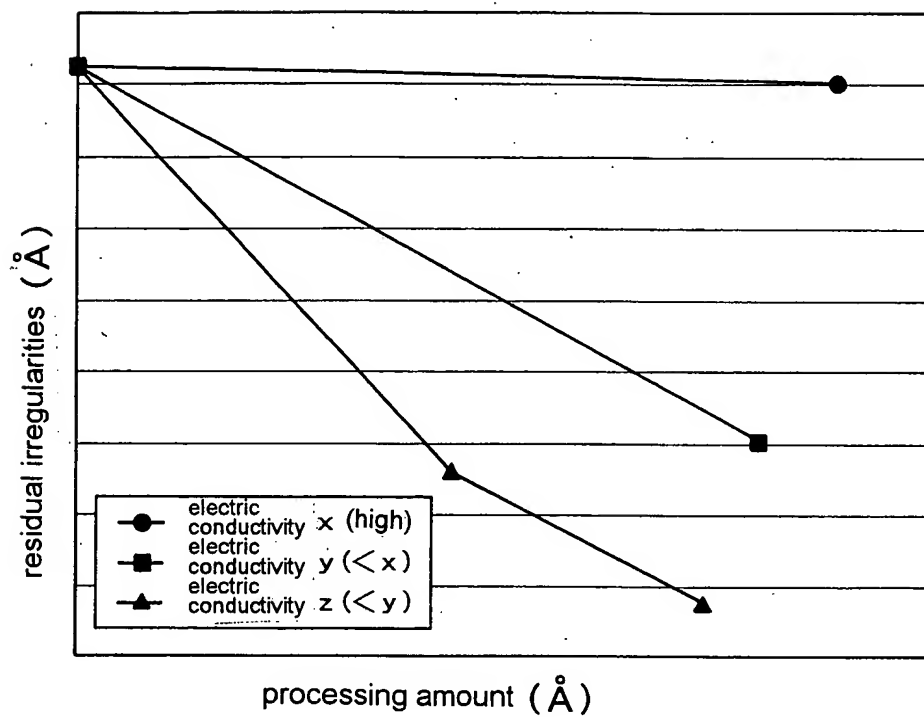


FIG. 11

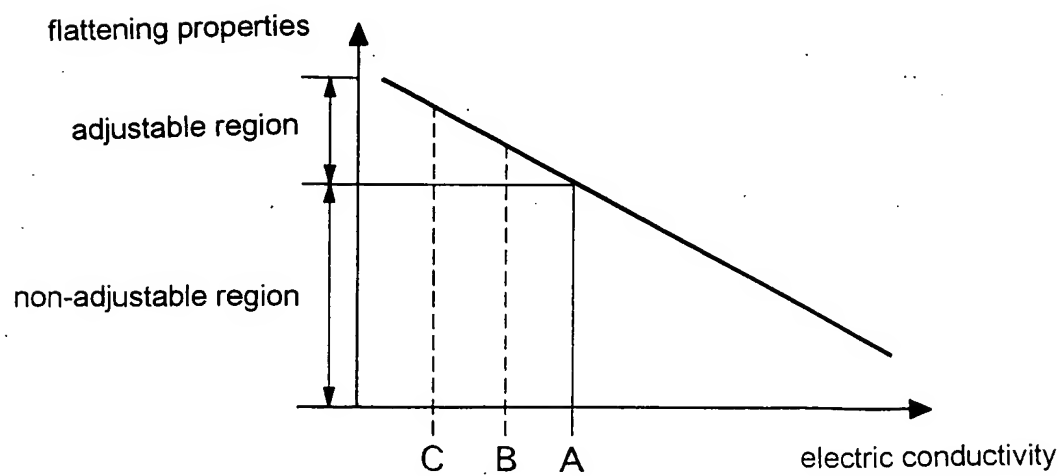


FIG. 12

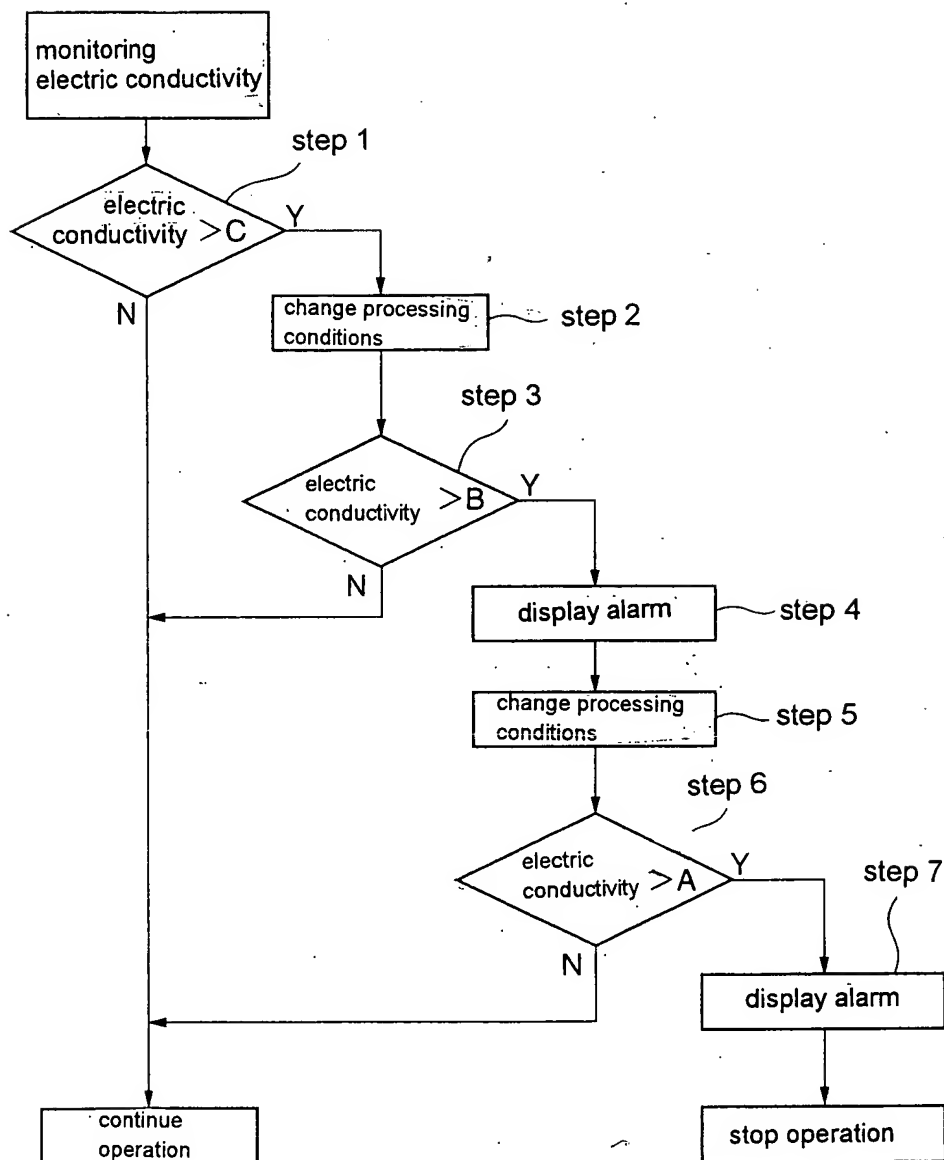




FIG. 14

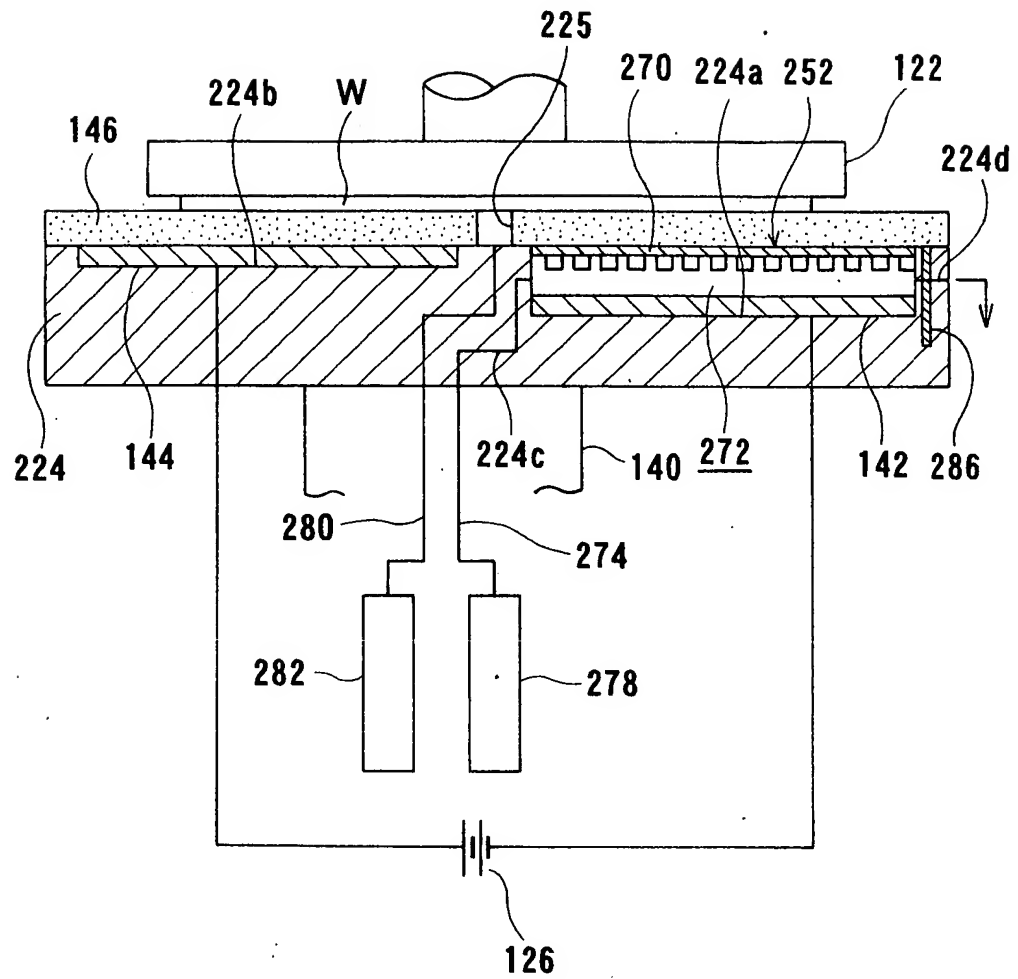


FIG. 15

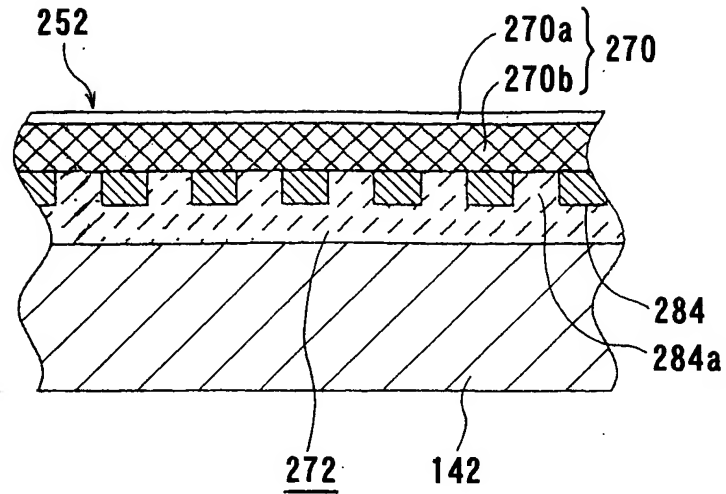


FIG. 16

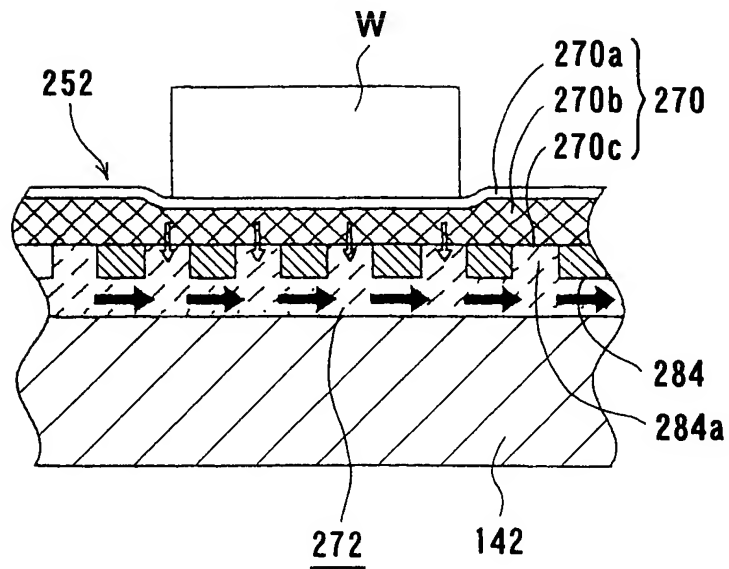
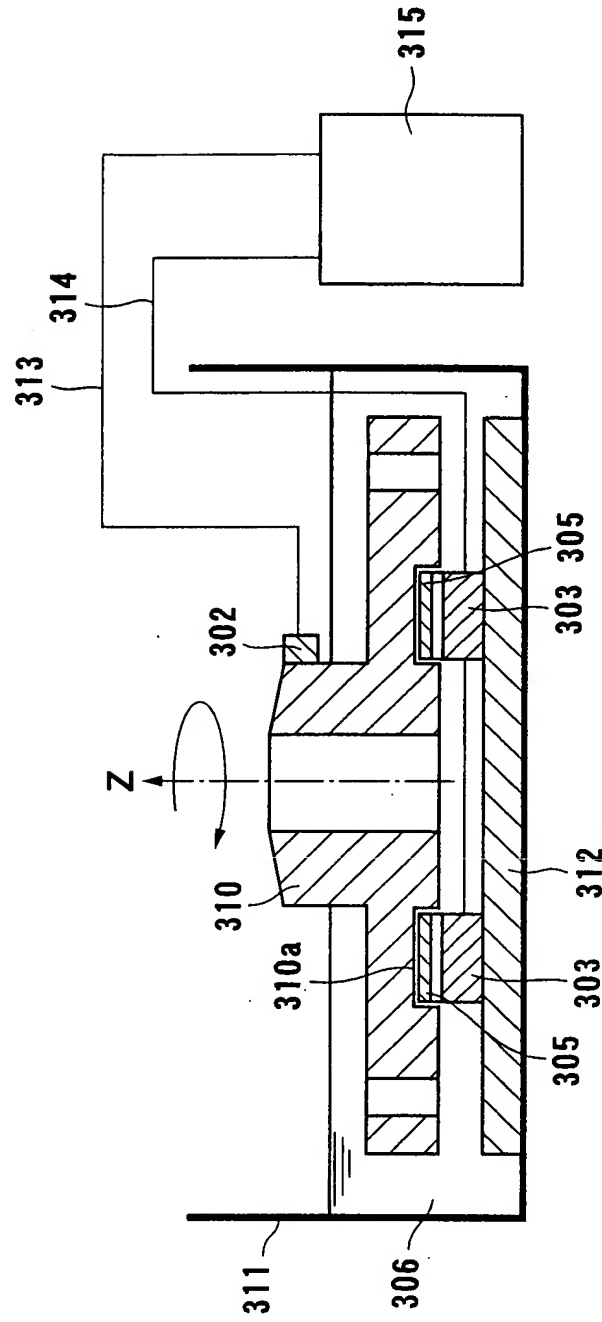


FIG. 17



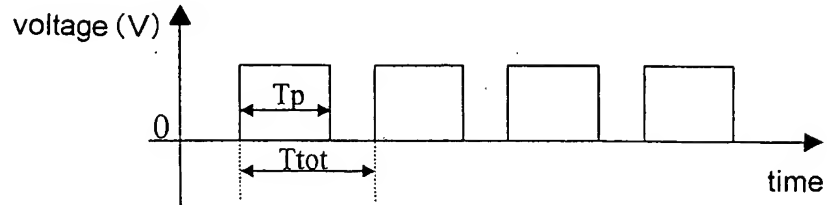
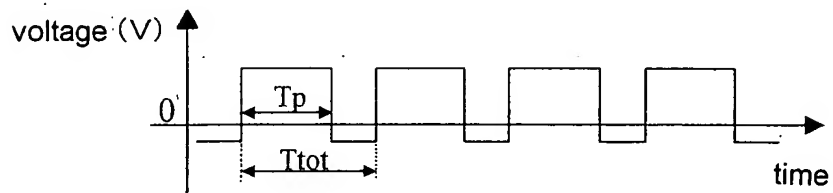
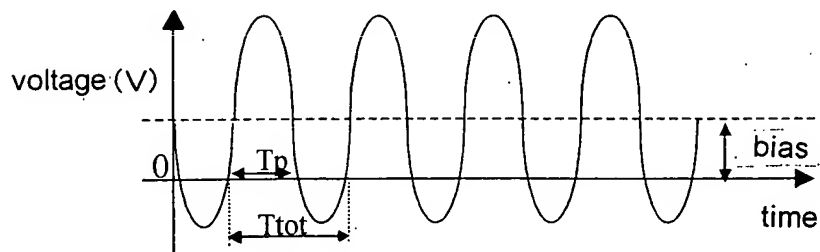
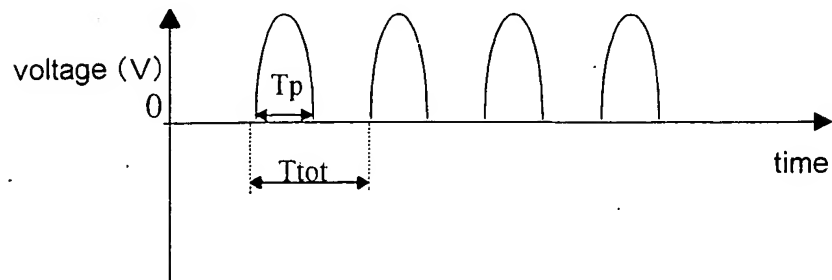
**FIG. 18A****FIG. 18B****FIG. 18C****FIG. 18D**

FIG. 19

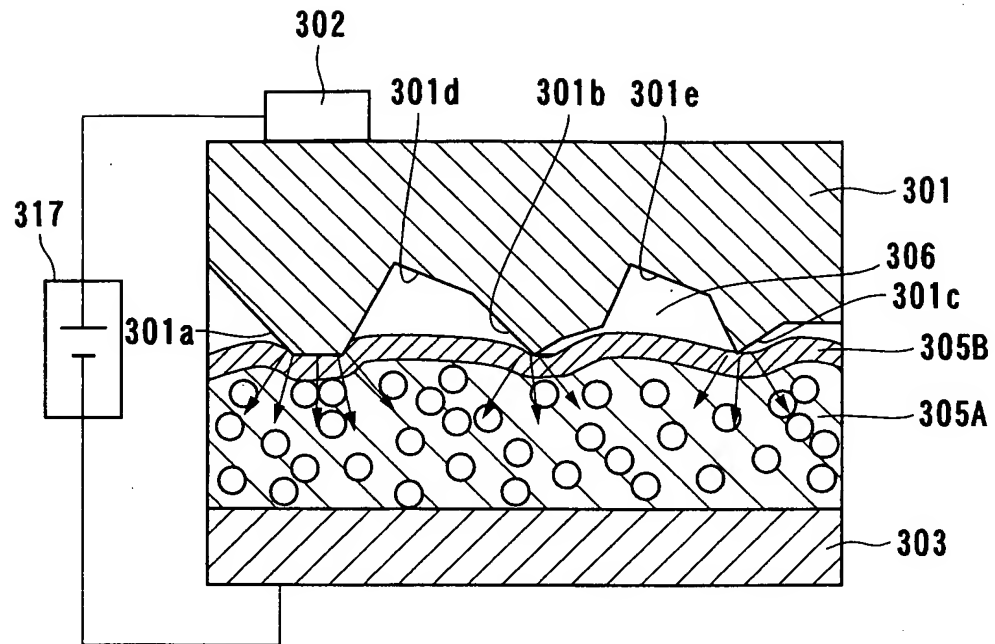




FIG. 20

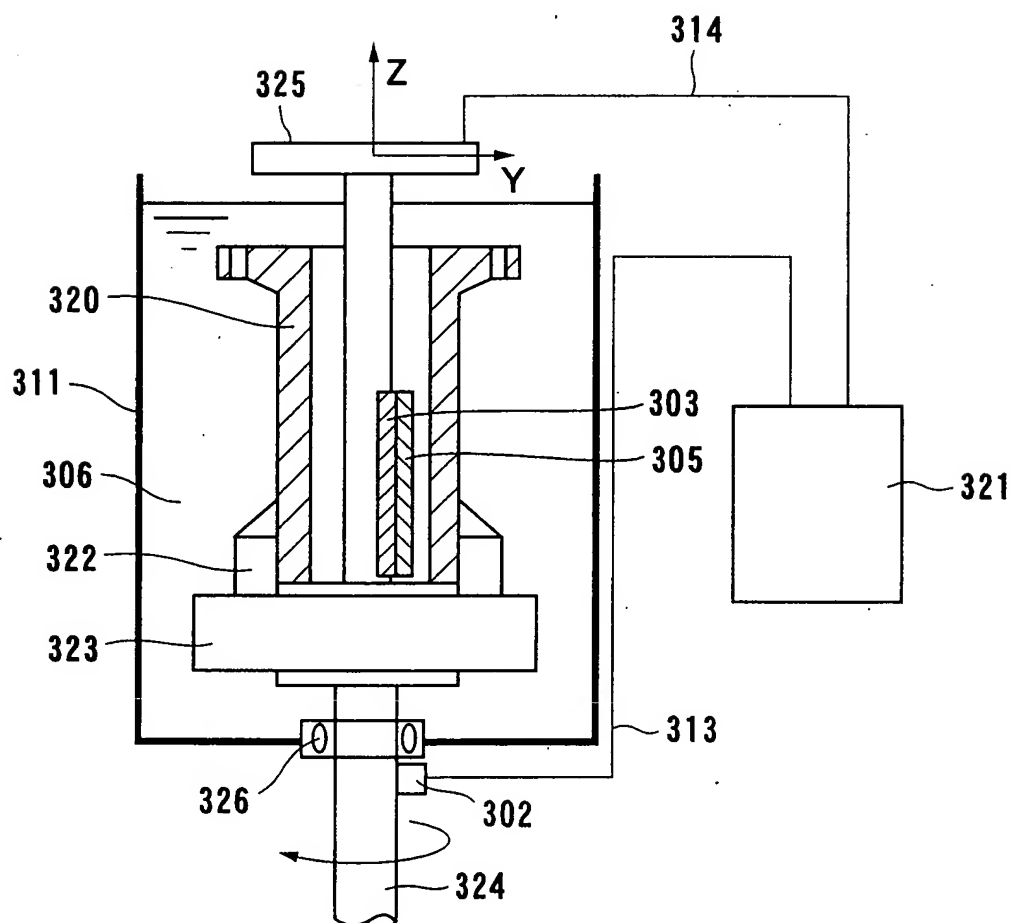


FIG. 21

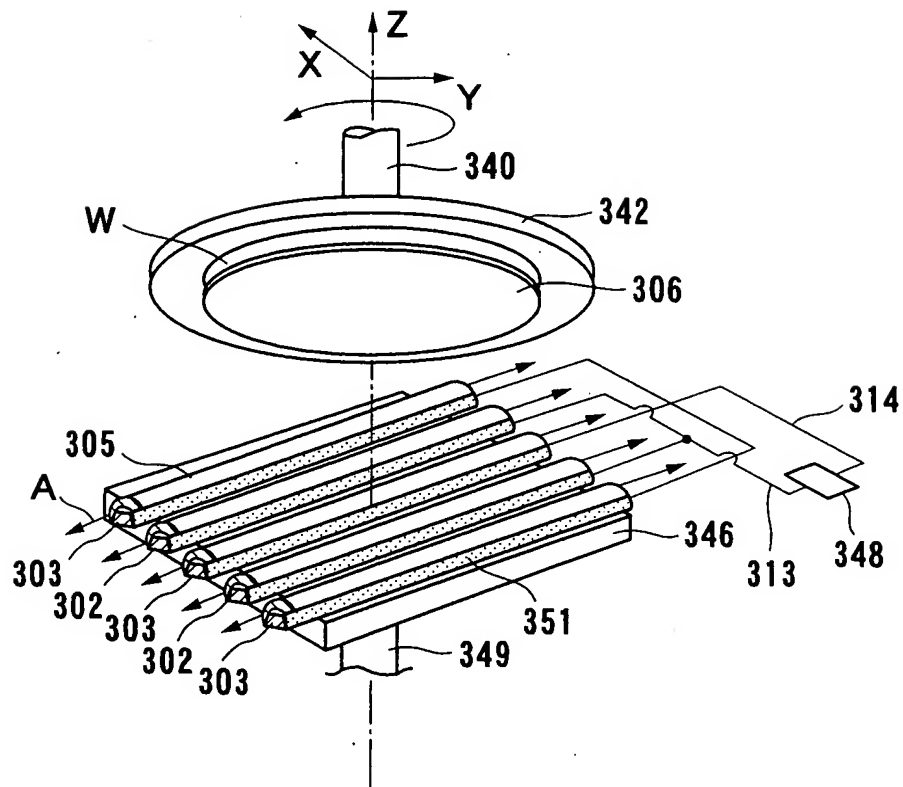
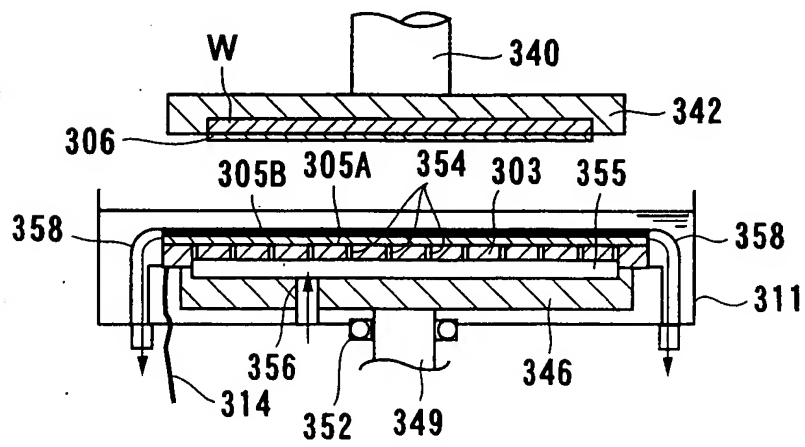


FIG. 22



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FIG. 23

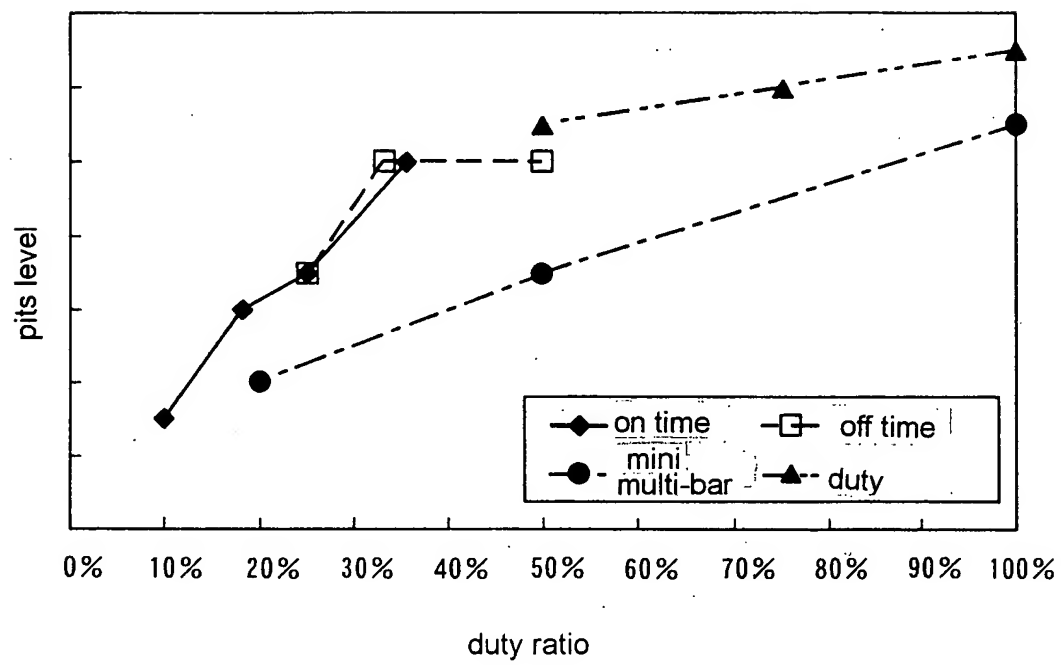
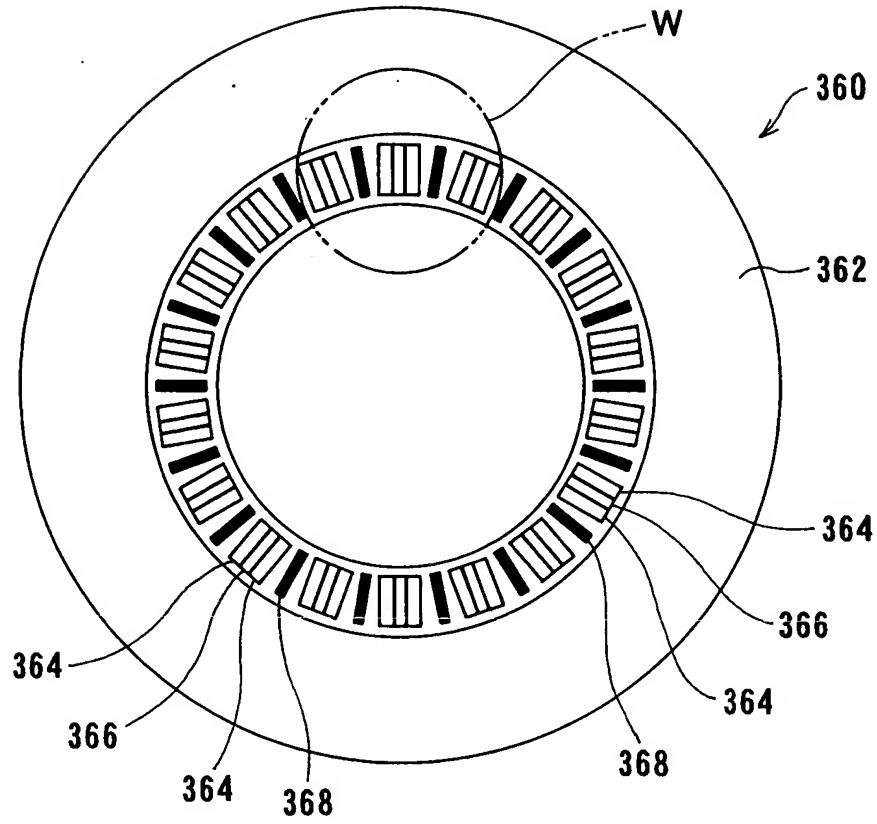
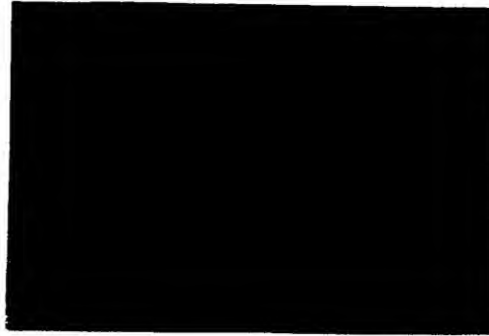
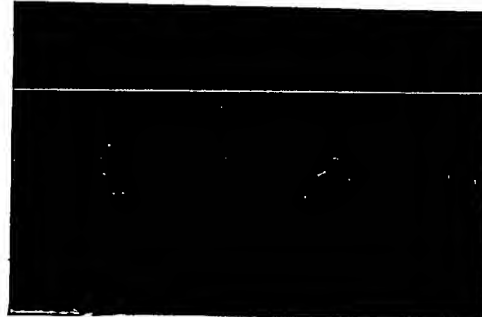


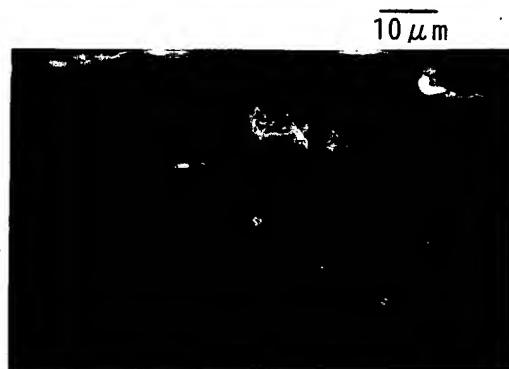
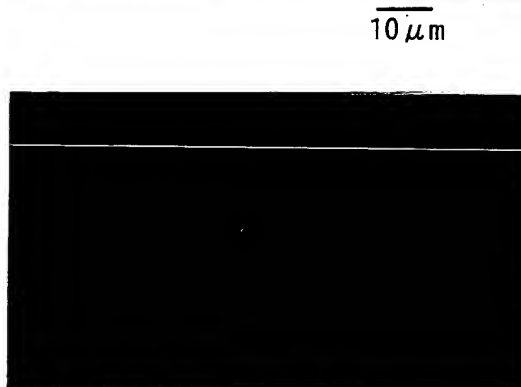
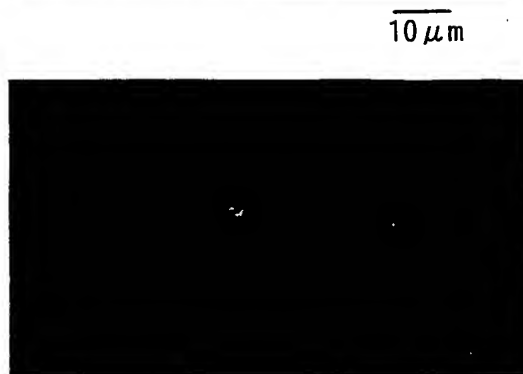
FIG. 24



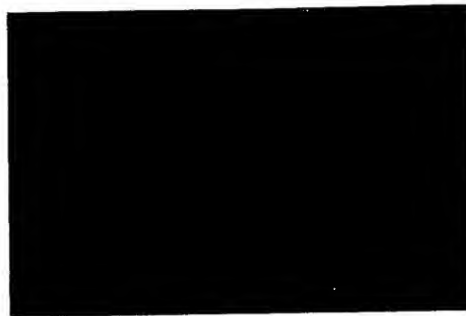
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*FIG. 25A* $10\ \mu\text{m}$ *FIG. 25B* $10\ \mu\text{m}$ *FIG. 25C* $10\ \mu\text{m}$ *FIG. 25D* $10\ \mu\text{m}$ 

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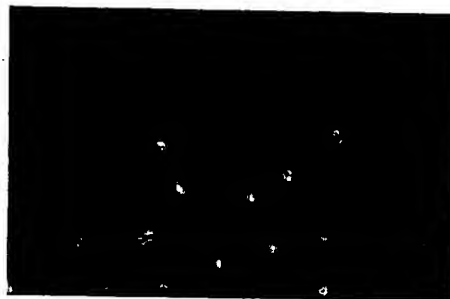
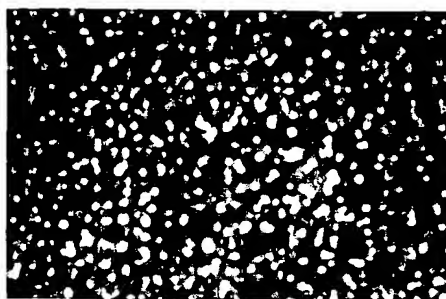
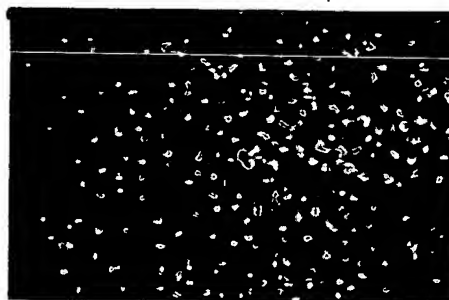
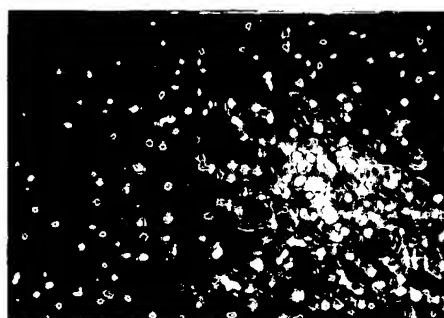
*FIG. 26A**FIG. 26B**FIG. 26C**FIG. 26D*

*FIG. 27*



$\overline{10\mu\text{m}}$

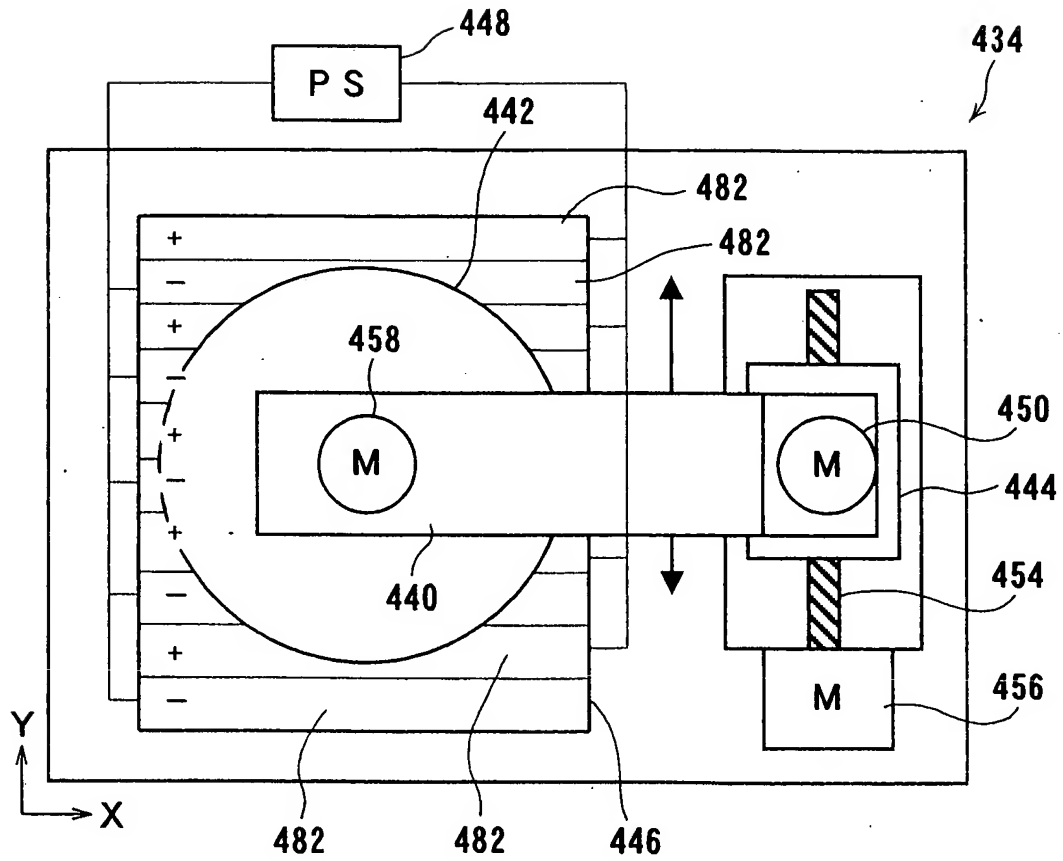
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*FIG. 28A* $10\ \mu\text{m}$ *FIG. 28B* $10\ \mu\text{m}$ *FIG. 28C* $10\ \mu\text{m}$ *FIG. 28D* $10\ \mu\text{m}$ 

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FIG. 29



**FIG. 30**

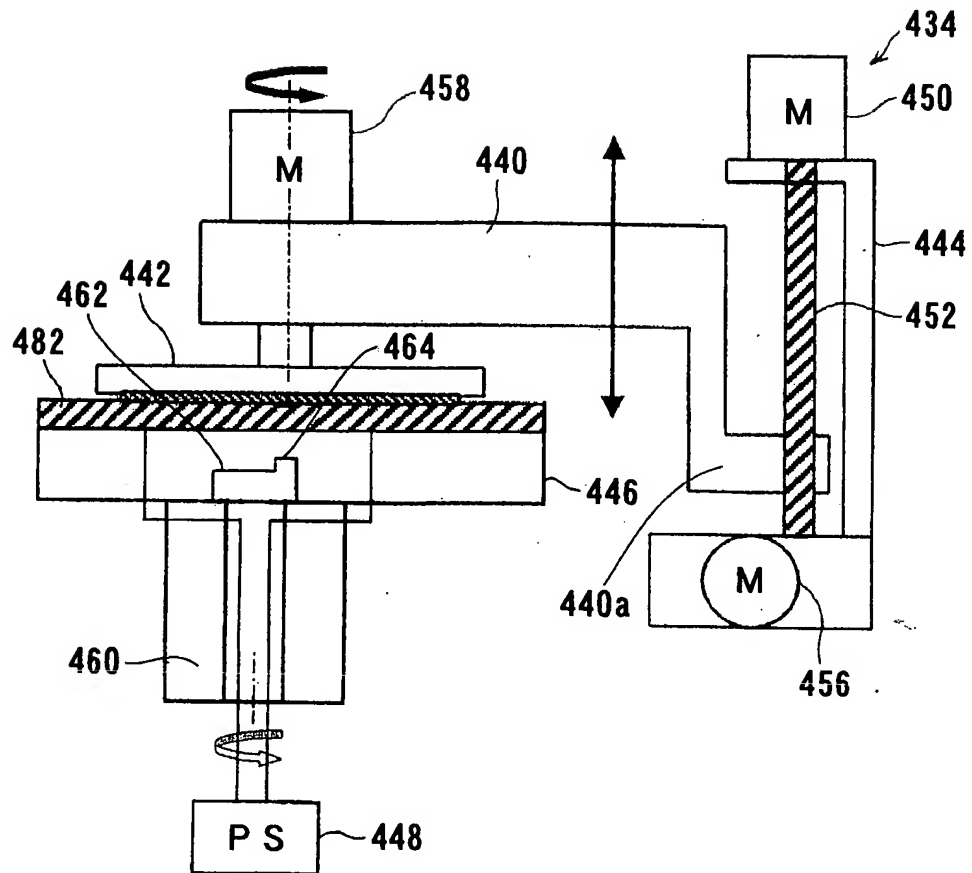


FIG. 31A

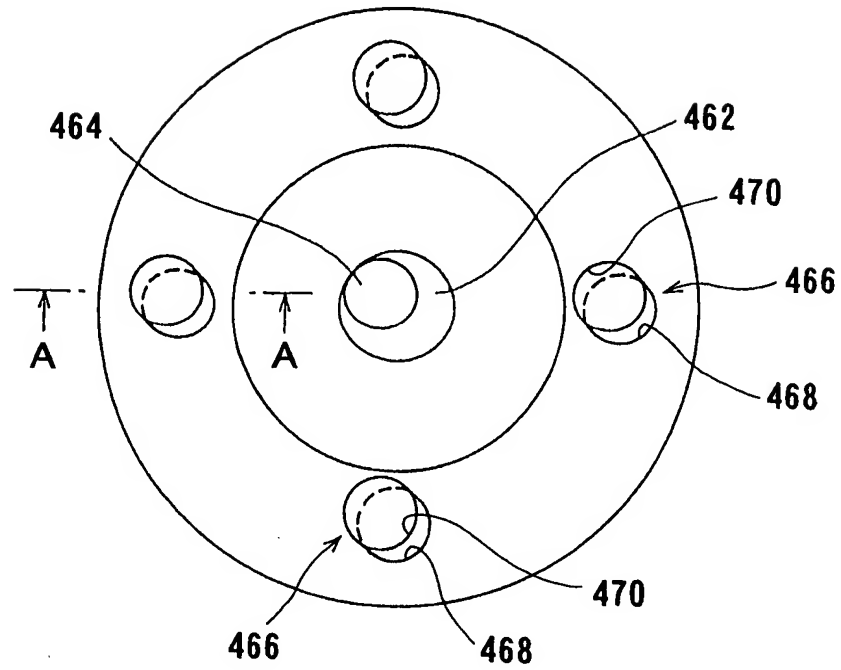


FIG. 31B

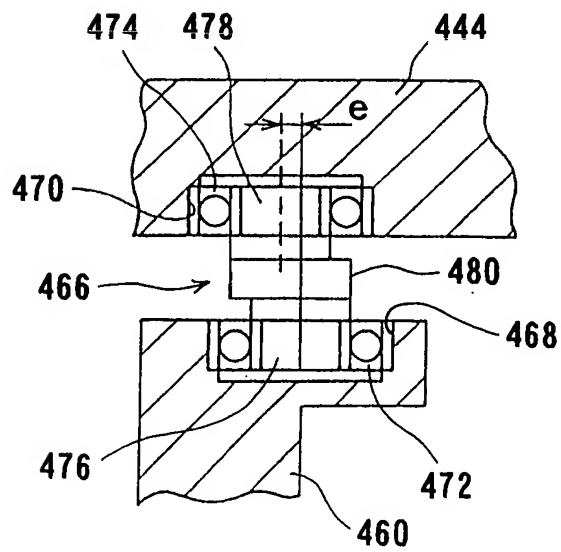


FIG. 32

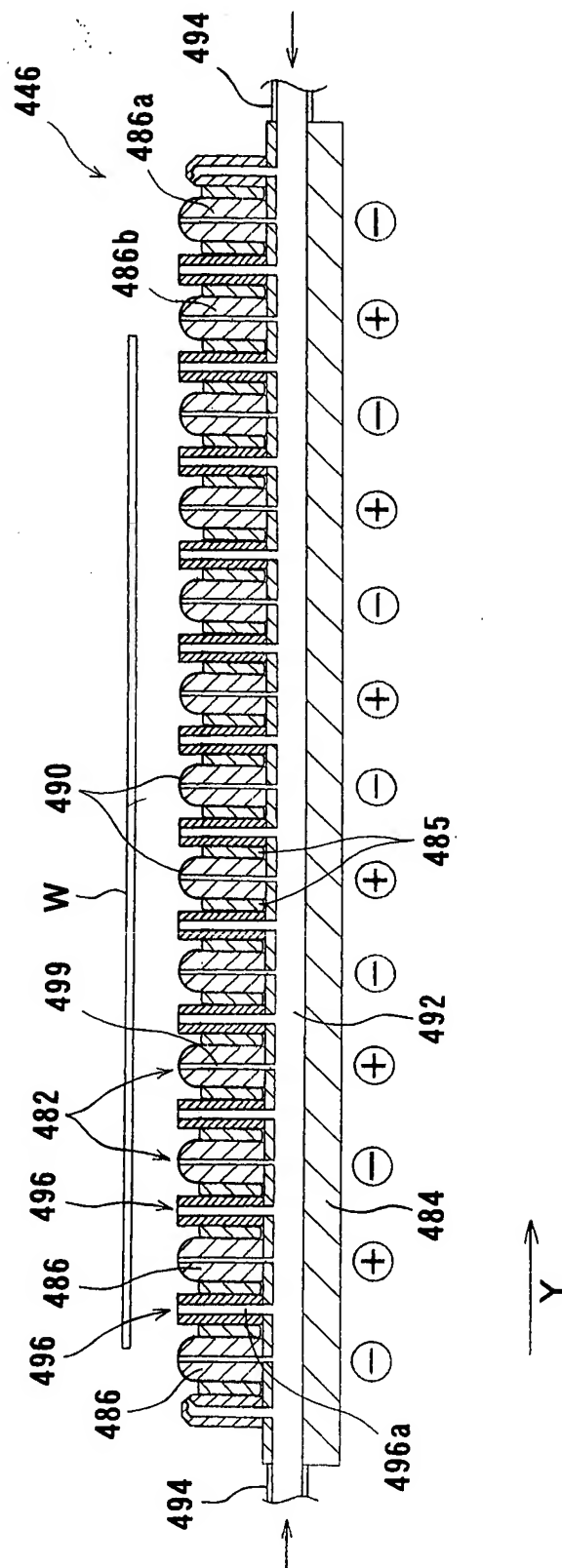


FIG. 33A

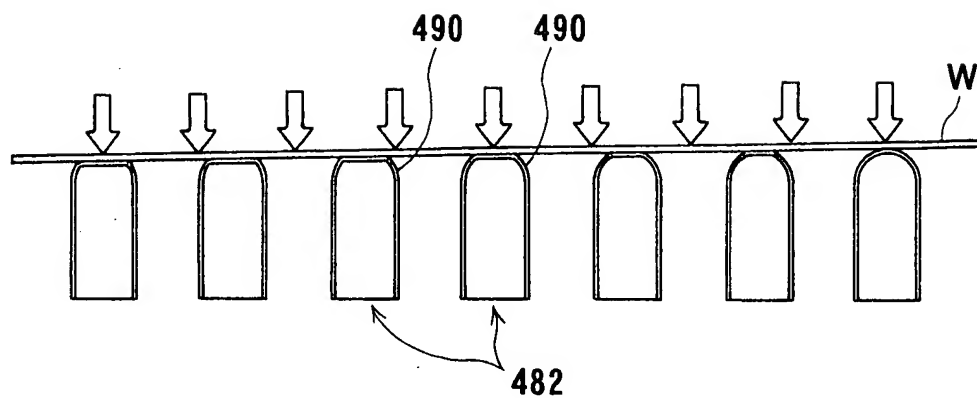


FIG. 33B

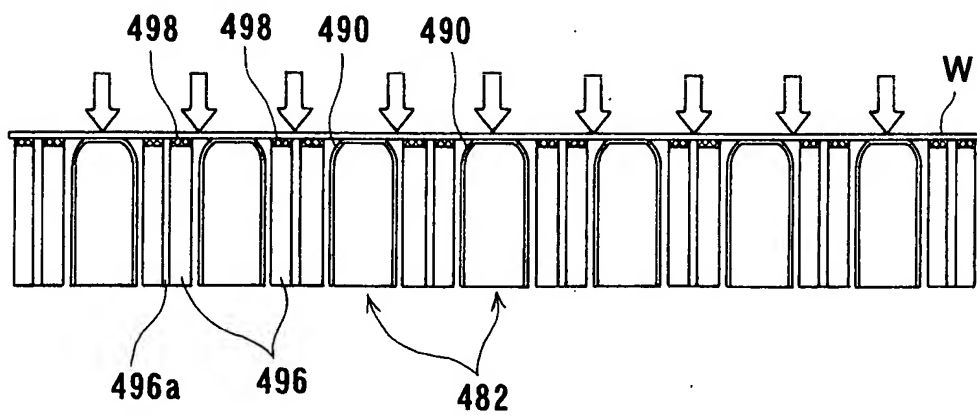


FIG. 34A

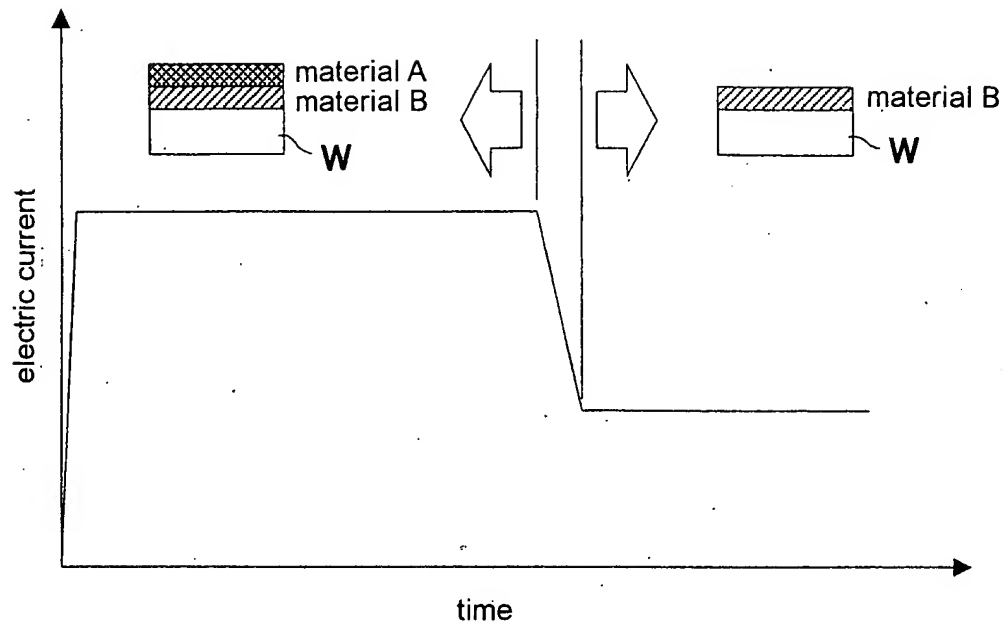


FIG. 34B

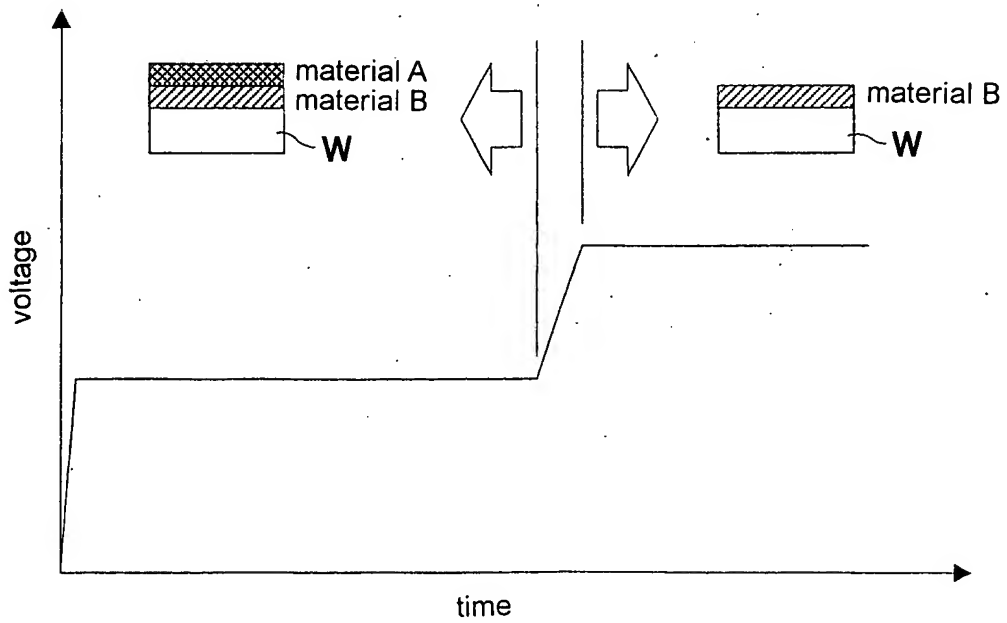


FIG. 35A

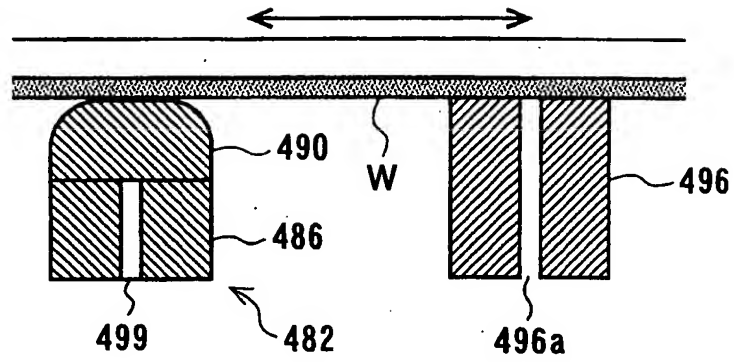


FIG. 35B

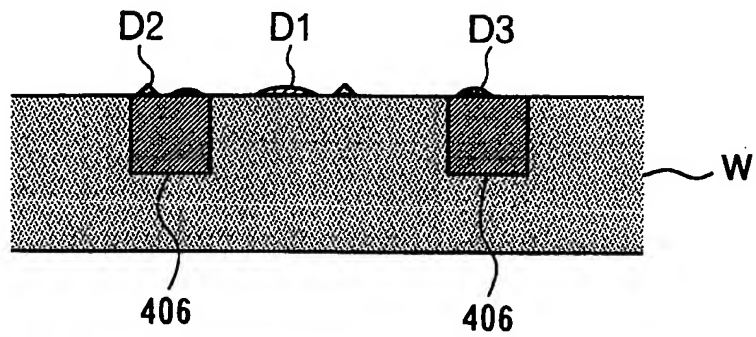
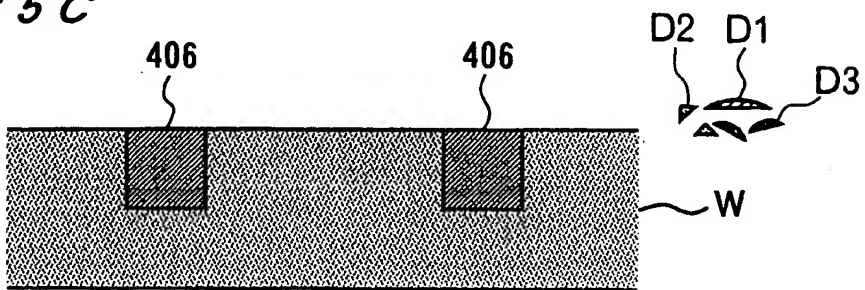


FIG. 35C



*FIG. 36*

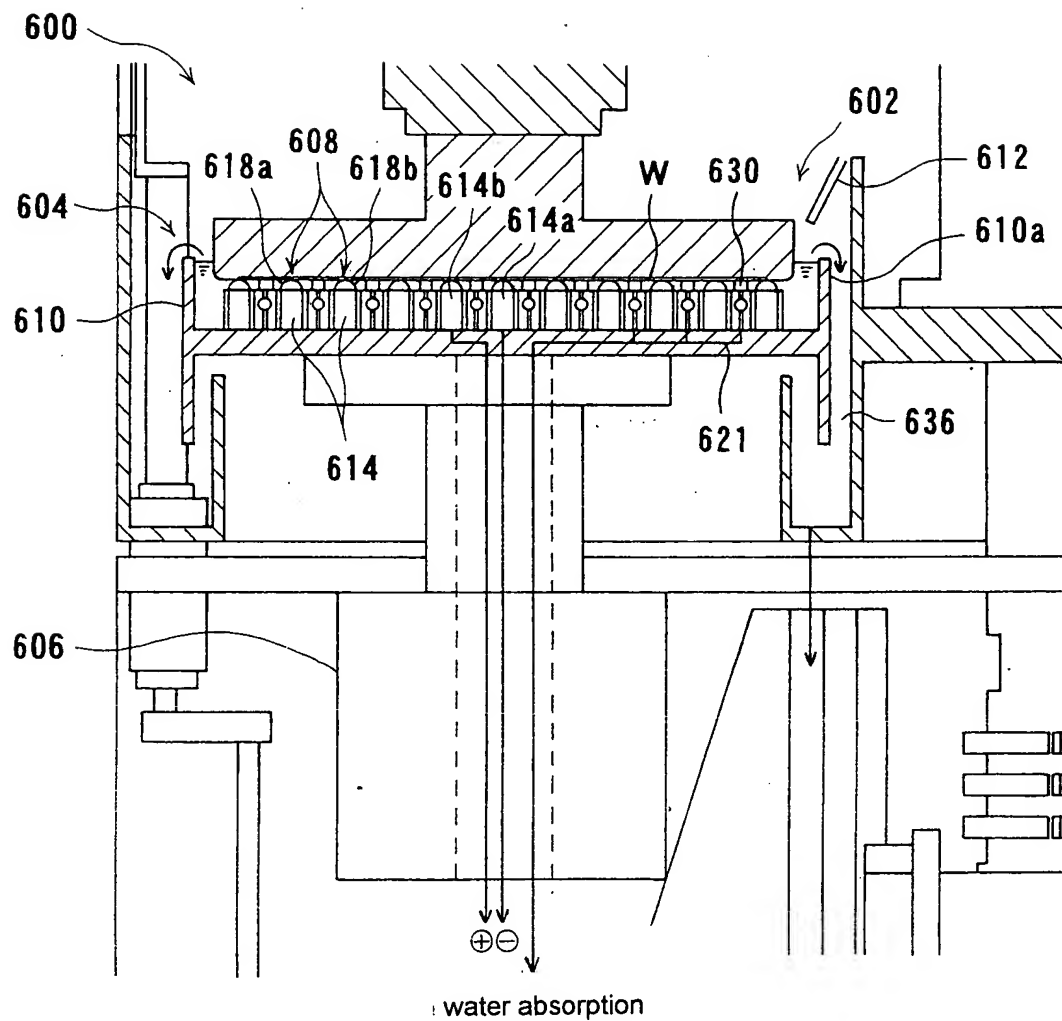




FIG. 37

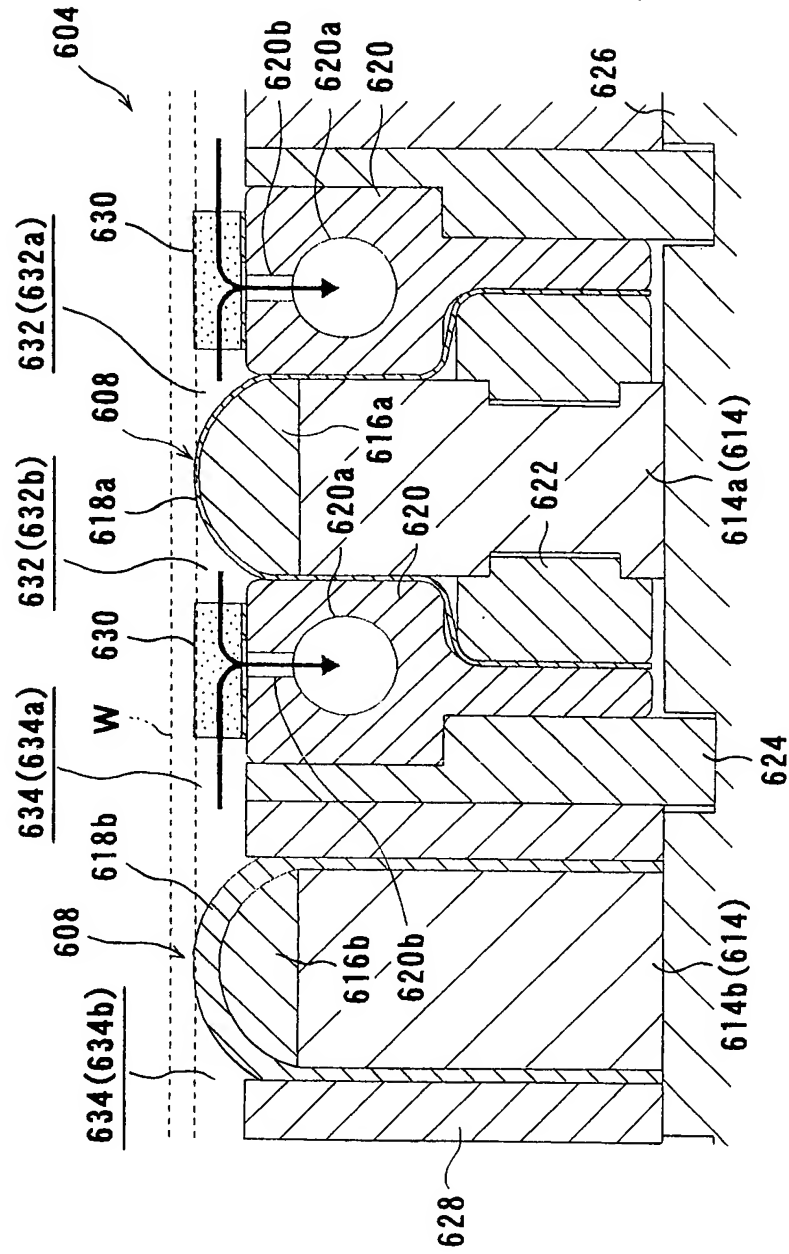


FIG. 38

